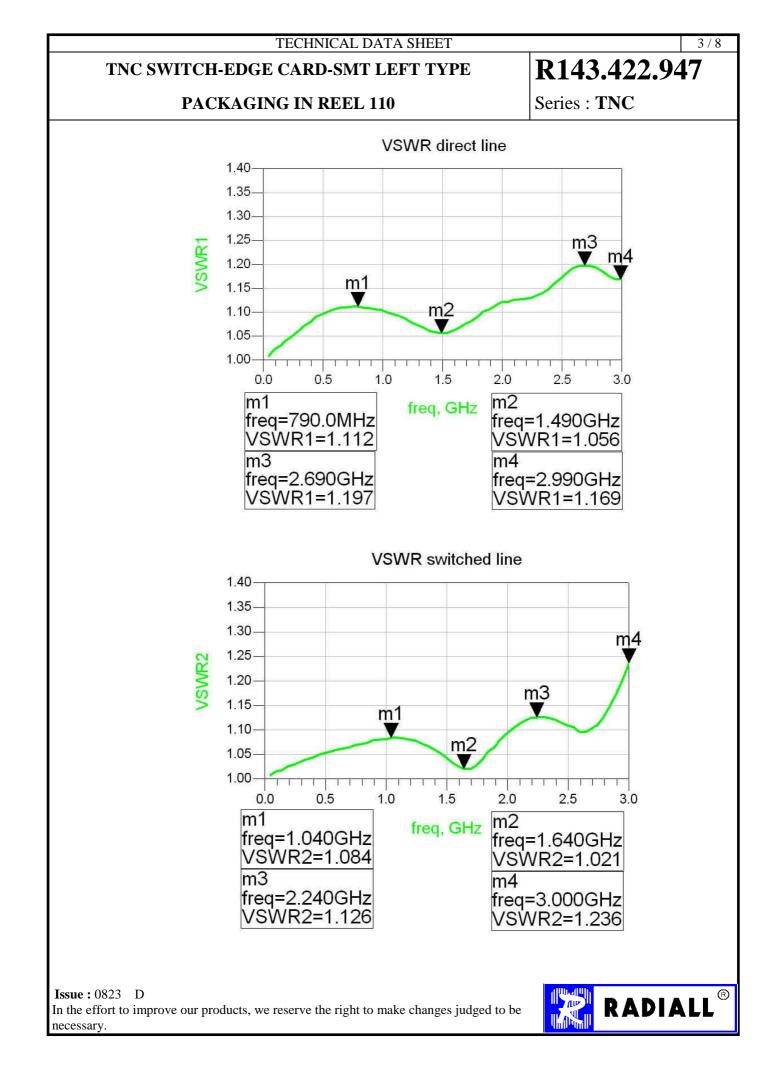
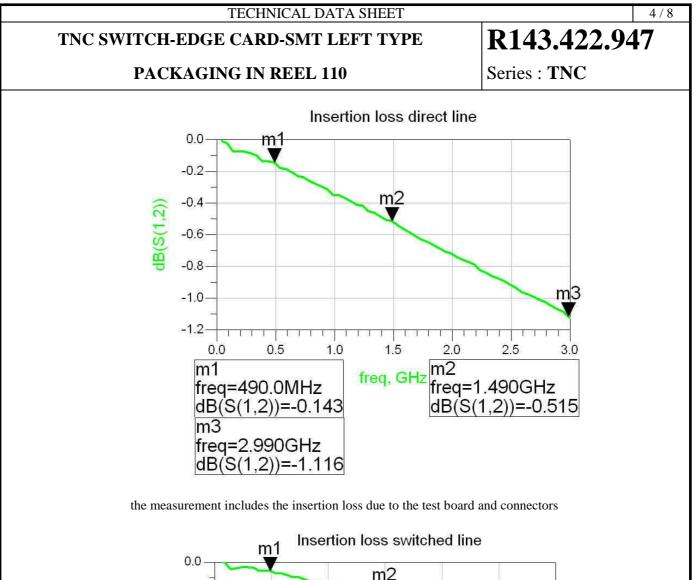
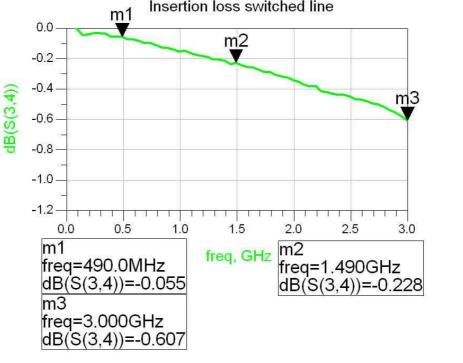


TECHNICAL DATA SHEET 2/8R143.422.947 TNC SWITCH-EDGE CARD-SMT LEFT TYPE Series : TNC **PACKAGING IN REEL 110 PACKAGING SPECIFICATION** Standard Unit Other 1301-RNT 408 4010 UEN rev C 110 'W' option **Contact us ELECTRICAL CHARACTERISTICS ENVIRONMENTAL** Impedance **-40/+85** ° C 50 Ω Operating temperature DC-3 GHz Frequency Hermetic seal NA Atm.cm3/s VSWR **1.1** + **0,1000** x F(GHz) Maxi Panel leakage NA -47 DB Typical Isolation at DC to 1 Ghz -43 DB Typical Isolation at 1 to 2 Ghz Isolation at 2 to 3 Ghz -40 DB Typical Insertion loss DC to 1 Ghz **0.1** $\sqrt{F(GHz)}$ dB Maxi 0.15 dB Maxi Insertion loss 1 to 2 Ghz Insertion loss 2 to 3 Ghz 0.2 dB Maxi NA - F(GHz)) dB Maxi RF leakage Voltage rating 300 Veff Maxi Dielectric withstanding voltage 500 Veff mini Insulation resistance **5000** MΩ mini **OTHERS CHARACTERISTICS** Power withstanding **80** W at 0.9 Ghz **50** W at 1.9 Ghz Assembly instruction Others : Action Mating Force : 20 N max **MECHANICAL CHARACTERISTICS** 15 N min Center contact retention Axial force – Mating end NA N mini (1) Do not apply force on the center contac before Axial force – Opposite end NA N mini Mounting the switch on PCB NA N.cm mini Torque Axial force side pin (1) Recommended torque Mating 22 N.cm Panel nut NA N.cm 100 Cycles mini Mating life Weight **20,9800** g



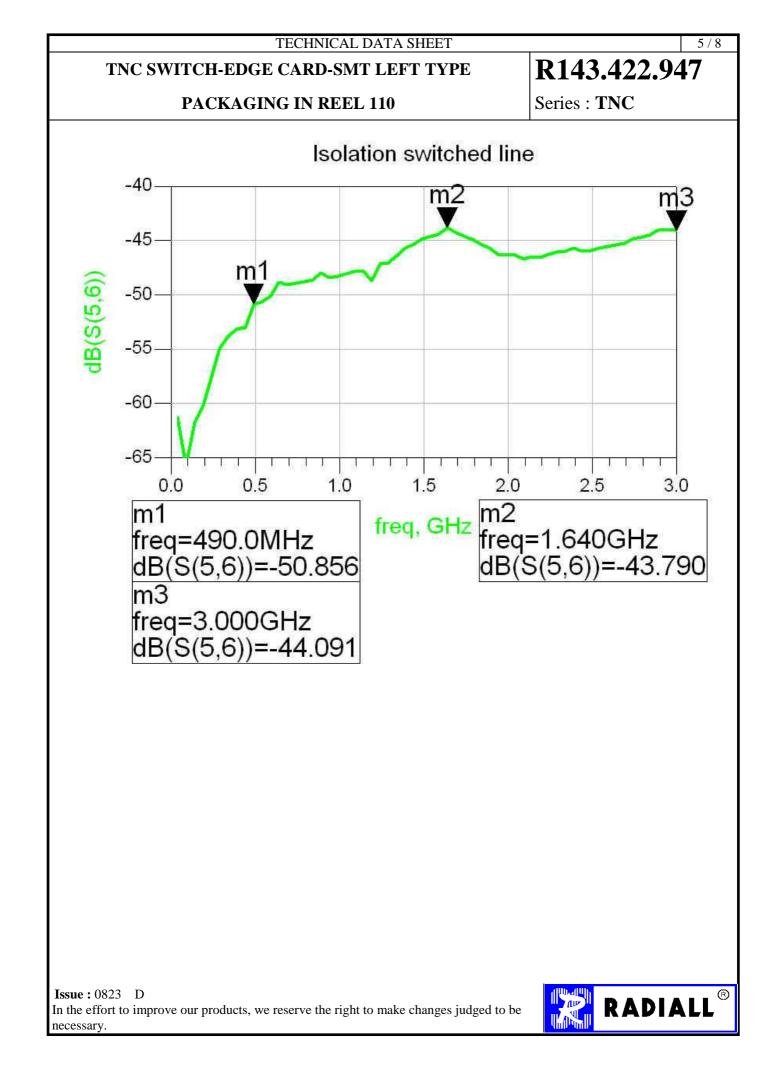






the measurement includes the insertion loss due to the test board and connectors





TECHNICAL DATA SHEET

TNC SWITCH-EDGE CARD-SMT LEFT TYPE

PACKAGING IN REEL 110

Series : TNC

R143.422.947

SOLDER PROCEDURE

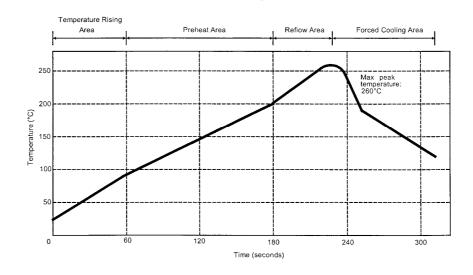
Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microsm (5.850 microsmet). Verify that the advest of the zone

We advise a thickness of 150 microm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

<u>NOTE</u> : The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



| Parameter | Value | Unit |
|----------------------------------|-----------|--------|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |



